

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## DSK32-MS THRU DSK310-MS

Product specification


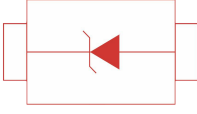
## Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- High forward surge current capability
- High temperature soldering guaranteed:  
250°C/10 seconds, 0.375(9.5mm) lead length,  
5 lbs. (2.3kg) tension

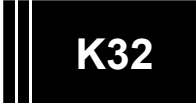
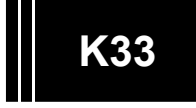






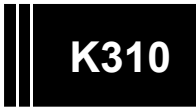
## MECHANICAL DATA

- Case: JEDEC SOD-123FL molded plastic body over passivated junction
- Terminals : Plated axial leads, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight: 0.0007 ounce, 0.02 grams

## Reference News

SOD-123FL	Schematic Diagram
	

## Marking

DSK32-MS	DSK33-MS	DSK34-MS	DSK35-MS	DSK36-MS
				
DSK37-MS	DSK38-MS	DSK39-MS	DSK310-MS	
				

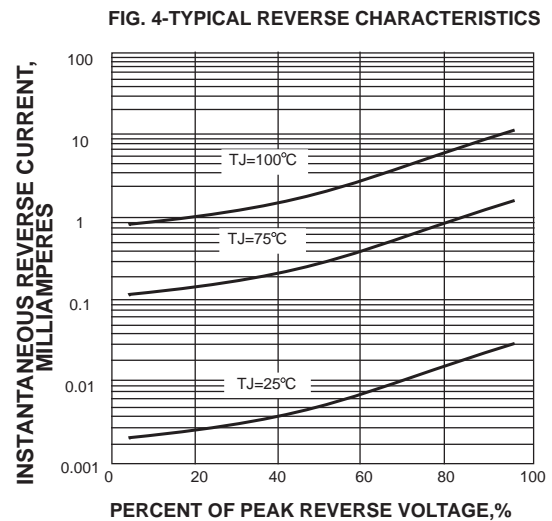
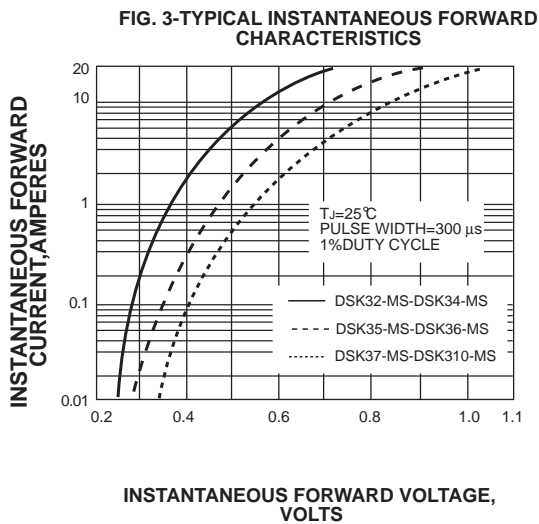
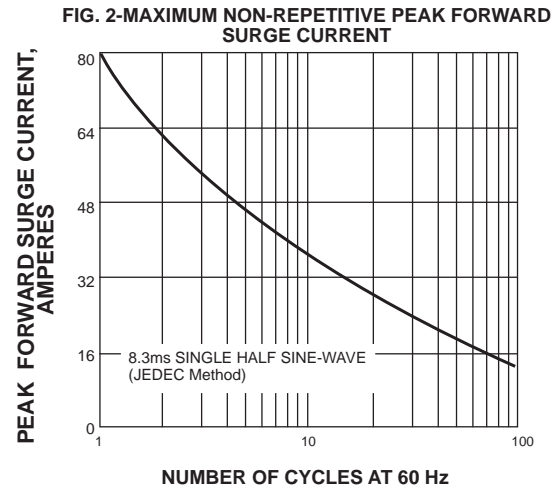
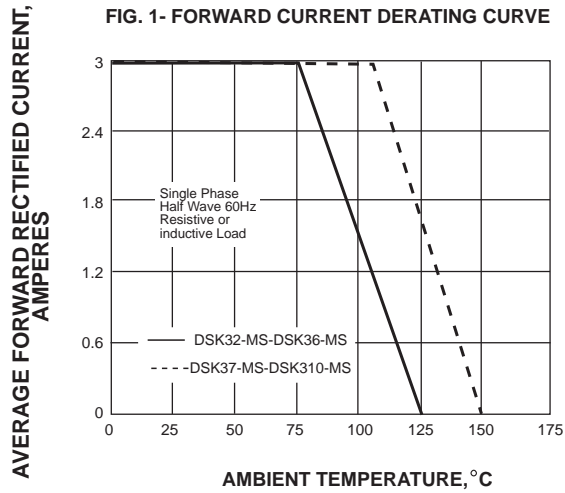
## Maximum Ratings and Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise specified

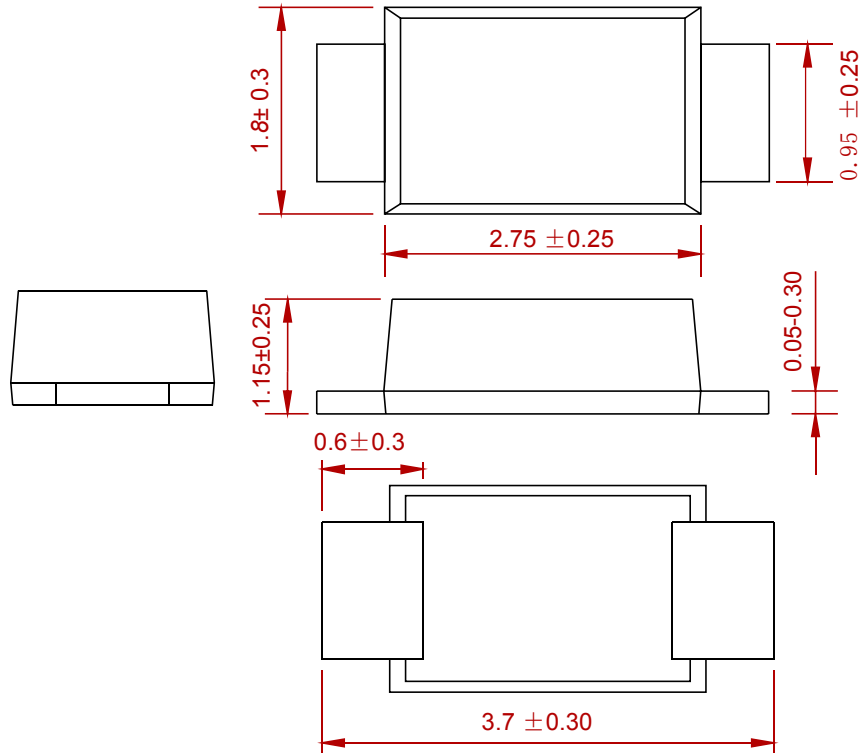
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	DSK32 -MS	DSK33 -MS	DSK34 -MS	DSK35 -MS	DSK36 -MS	DSK37 -MS	DSK38 -MS	DSK39 -MS	DSK310 -MS	Unit
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	20	30	40	50	60	70	80	90	100	Volts
Maximum RMS voltage	V <sub>RMS</sub>	14	21	28	35	42	49	56	63	70	Volts
Maximum DC blocking voltage	V <sub>DC</sub>	20	30	40	50	60	70	80	90	100	Volts
Maximum average forward rectified current	I <sub>(AV)</sub>	3.0									Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	80.0									Amps
Maximum instantaneous forward voltage at 3.0A	V <sub>F</sub>	0.52	0.55		0.70		0.85			Volts	
Maximum DC reverse current at rated DC blocking voltage T <sub>A</sub> =25°C T <sub>A</sub> =100°C	I <sub>R</sub>	0.5									mA
		20.0					10.0				
Operating junction temperature range	T <sub>J</sub>	-50 to +125					-50 to +150				°C
Storage temperature range	T <sub>STG</sub>	-50 to +150									°C

## RATINGS AND CHARACTERISTIC CURVES DSK32-MS THRU DSK310-MS

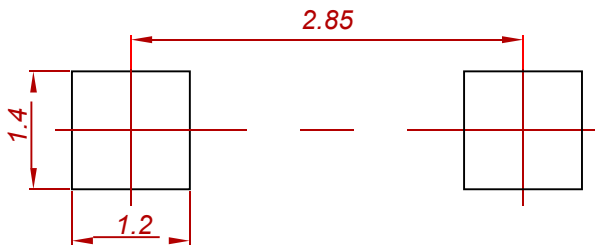


**PACKAGE MECHANICAL DATA**



*Dimensions in millimeters*

**Suggested Pad Layout**



**Note:**  
 1. Controlling dimension: in millimeters.  
 2. General tolerance:  $\pm 0.05$  mm.  
 3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
DSK32-MS THRU DSK310-MS	SOD-123FL	3000

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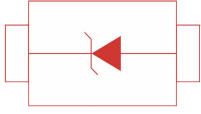
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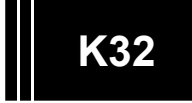
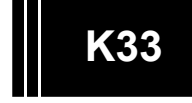
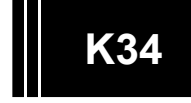
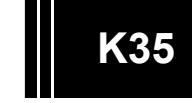

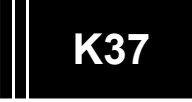

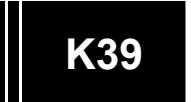
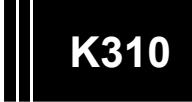
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PACKAGE OUTLINE	Schematic Diagram
	

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at rated DC blocking voltage      T <sub>A</sub> =25°C T <sub>A</sub> =100°C	I <sub>R</sub>	0.5									mA
		20.0					10.0				
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